

Technical Information

6540 Silver-Palladium Substrate Plug Conductor Paste

The thick film silver composition 6540 was designed for plugging through holes in 0.010" to 0.025" thick alumina substrate. It provides a solid, low resistance interconnect for two sided substrates, while allowing increased circuit density. It does not contain cadmium, lead, nickel or highly toxic organic solvents. Key features include:

- High Electrical and Thermal Conductivity
- High Adhesion
- Low Shrinkage, No Separation from Side Walls
- Adheres to Most LTCC Tape
- For Use with Bladder Machine or Stencil

TYPICAL FIRED FILM CHARACTERISTICS⁽¹⁾

Metallurgy	Ag-Pd
Resistivity	10 – 40 milliohms / square at 25 μm fired thickness
Adhesion⁽⁴⁾	> 20 N

- (1) Typical properties are based on testing of several batches under various processing conditions. They are not intended as specification limits.
- (2) The adhesion test consists of attaching 20 AWG tinned copper wire to .080"x.080" pads, by dipping in 225 +/-5°C solder for 5 seconds. The wires are then bent 90 degrees and pulled at constant speed, while a force gauge records the peel strength. However, this product is not recommended for directly soldering to it.

COMPOSITION PROPERTIES

Viscosity:	500 - 1000 Kcps, when measured with Brookfield HBT, Spindle #14, utility cup, 10 RPM, 25°C.
Specific Gravity:	5.0 – 5.5 g/cm ³
Recommended Thinner:	KOARTAN A-1039

RECOMMENDED PROCESSING PROCEDURE

Printing: Printing with a 3-5 mil thick stencil, or application with a bladder machine is recommended. Pulling vacuum through a porous stone aids in obtaining good plugs if the stencil method is used. Placing an absorbent paper under the substrate also helps in draining the excess liquid and results in a denser mass, regardless of the filling method.

Drying: Wet prints should be allowed to stabilize for 5-10 minutes prior to drying. Dry for 15-30 minutes in a convection oven or belt dryer at 100°C-150°C.

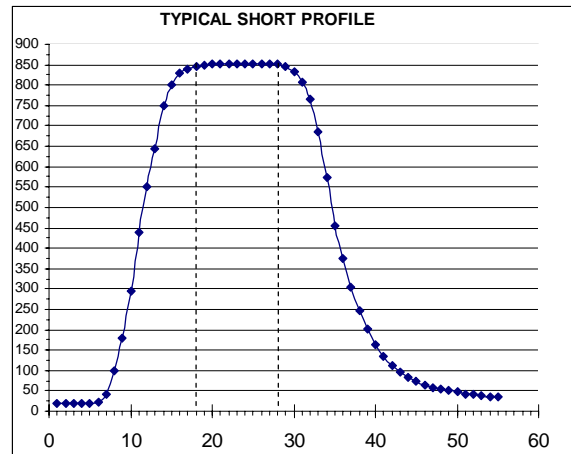
Firing: Firing in air using a belt furnace and a 36-60 minute profile, with 10 minutes at a peak temperature of 850°C is recommended. Air flow rates must be optimized to ensure that the products of binder burn-off discharge properly and create a fully oxidizing atmosphere in the muffle.

Application Notes: Regardless of the filling method used, it is recommended that the filling operation be continued after the holes are apparently filled. This creates a denser film and assures complete fill when very many holes are to be filled at once.

For thicker substrates it is recommended that the filled parts be dried longer, but at lower drying temperature.

If excess dried paste protrudes on either side of the dried substrate, it can gently be removed with a clean, lint-free wipe, sparingly moistened with high purity

isopropyl alcohol or other solvent used for cleaning screens and stencils. This may leave a slight depression, which can be filled when printing the remaining circuit layers.



Storage and Shelf Life: Store in tightly capped containers at room temperature. Shelf life is 6 months for unopened jars. Under ordinary conditions of storage and use the product should not require thinning. However, solvent loss during extended printing runs may be corrected by incorporating up to 0.5% of Koartan A-1039 thinner.

The information presented herein is based on data believed to be dependable and is accurate and reliable to the best of our knowledge and belief, but not guaranteed to be so. Koartan Company assumes no liability arising from the use of this product or the information provided herein. Nothing herein is to be construed as recommending any practice or any product in violation of any patent or in violation of any law or regulation.